



- 10/100/1000 Gigabit Base-T for Ethernet Applications
- Transmit open circuit inductance (OCL): 350µH (MIN @ 100KHz, 0.1Vrms with 8mA DC Bias)
- Meets IEEE 802.3 specification
- Industrial Operating Temp: -40°C to +85°C



Electrical Specifications @ 25°C

OCL(µH Min) @ 100KHz, 0.1V With 8mA DC Bias	Turns Ratio (±2%)	Return Loss (dB Min)			
		1-30MHz	30-60MHz	60-80MHz	80-100MHz
350	1CT:1CT	-18	-16	-14	-12

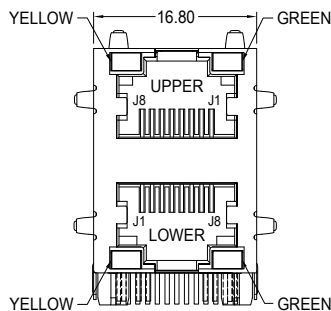
Electrical Specifications @ 25°C

Insertion Loss (dB Max)	Cross Talk (dB Typ)		CMR (dB Min)	HiPot Vrms
	1-60MHz	60-100MHz		
0.1-100 MHz	-35	-25	-25	1500
-1.1	-35	-25	-25	1500

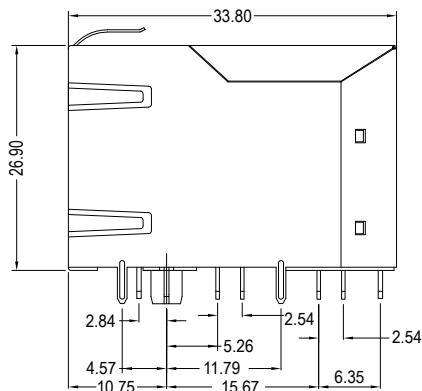
\*All specifications subject to change without notice.

MECHANICAL

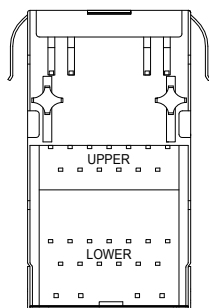
Dimensions: mm



Front View



SideView



BottomView

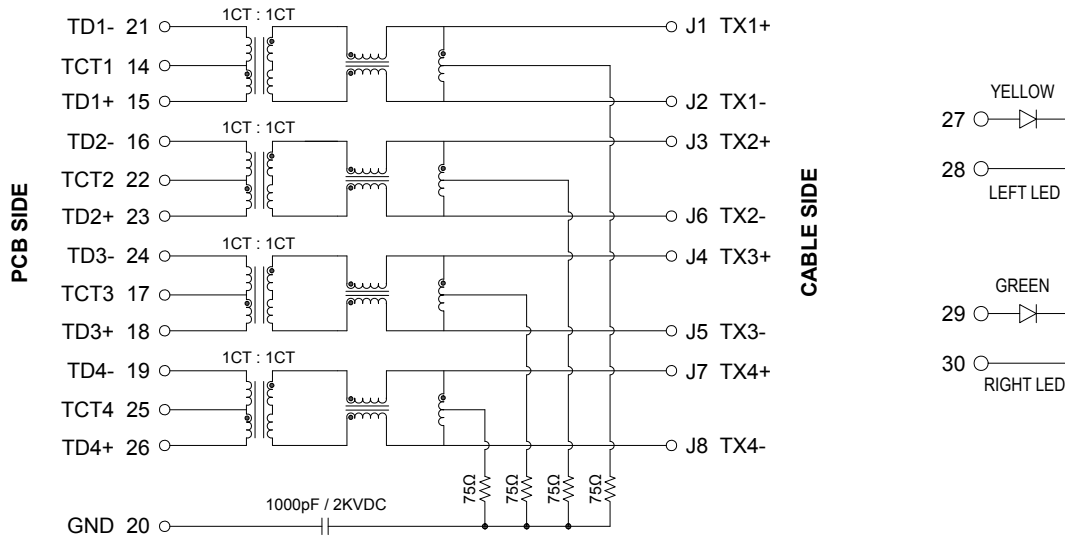


Top View

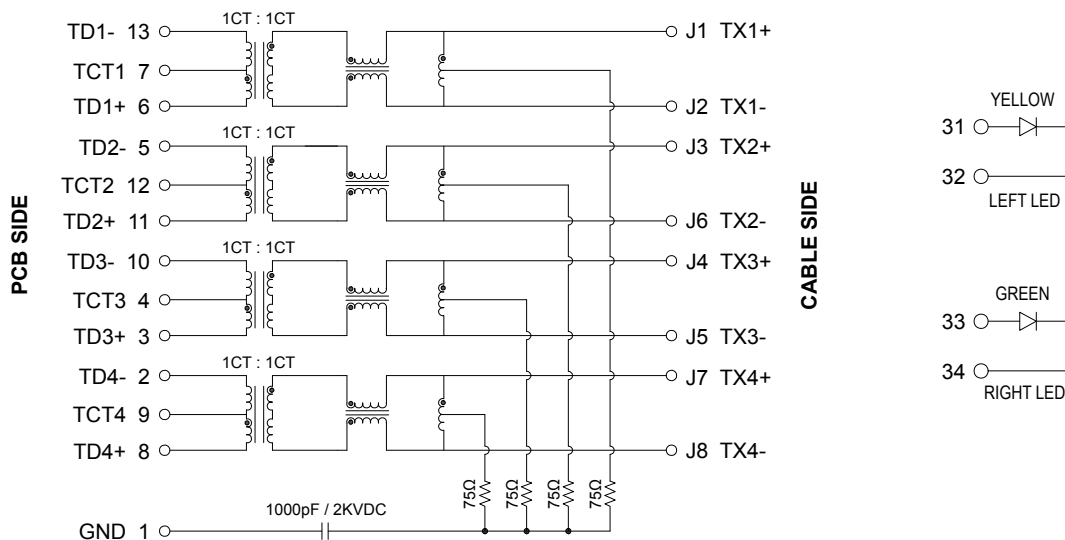


**SCHEMATICS**

**LOWER PORT**



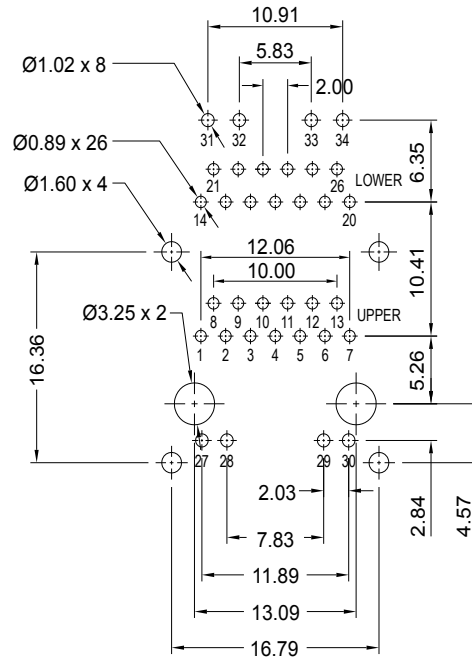
**UPPER PORT**



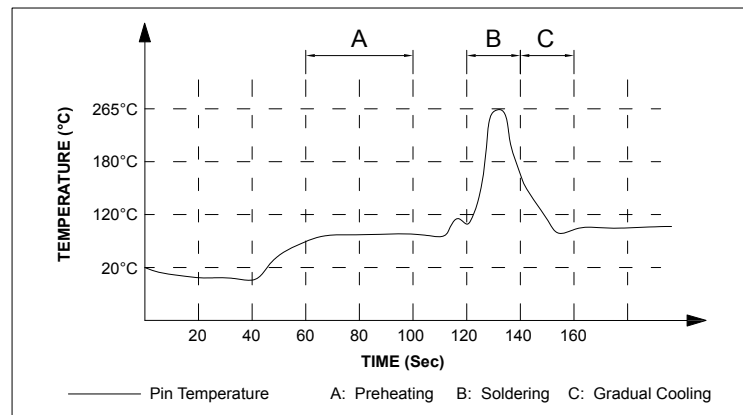
Emitting Color	$\lambda_p$ (nm)	$V_F@I_F=20mA$	$I_R@V_R=5V$
GREEN	565	1.8~2.6V	10 $\mu$ A Max
YELLOW	585	1.8~2.6V	10 $\mu$ A Max



## PCB LAYOUT



## SUGGESTED WAVE SOLDER PROFILE



- (1) Peak Temperature: 265°C Max  
 (2) Peak Temperature Time: 5 Sec Max  
 (Note) Melting point of Tin: 219°C

## NOTES

- Connector Materials:  
 Housing Material: Thermoplastic UL94V-0  
 Contact/Shield: Copper Alloy  
 Shield Plating: Nickel  
 Contact Plating: Gold 6 $\mu$  min in contact area
- Wave Solder Peak Temperature: 265°C Max, 5 Sec Max